

Product Change Notification - RMES-24CGNQ027

Date:

07 Feb 2019

Product Category:

8-bit Microcontrollers

Affected CPNs:

7

Notification subject:

CCB 3676 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L DFN (4x4x0.9mm) package.

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L DFN (4x4x0.9mm) package.

Pre Change:

Assembled at NSEB using 8600 die attach material

Post Change:

Assembled at NSEB using 8600 die attach material or Assembled at MMT using 3280 die attach material

Pre and Post Change Summary:

	Pre Change	Post Change					
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)						
Wire material	Au	Au	Au				
Die attach material	8600	8600	3280				
Lead frame Material	A194	A194	A194				
Molding compound material	G700LTD	G700LTD	G700LTD				

Impacts to Data Sheet:

None

Reason for Change:

To improve productivity and on-time delivery performance by qualify MMT as an additional assembly



site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

March 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2019				March 2019					
Workweek	05	06	07	08	09	10	11	12	13	14
Initial PCN Issue Date		Х								
Qualification Report Availability										Х
Final PCN Issue Date										Х

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

February 7, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-24CGNQ027_Qual_Plan.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

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Affected Catalog Part Numbers (CPN)

PIC12F609-E/MD PIC12F609-I/MD PIC12F609T-I/MD PIC12F615-E/MD PIC12F615-H/MD PIC12F615-I/MD PIC12F615T-I/MD PIC12F615T-I/MD029 PIC12F629-E/MD PIC12F629-I/MD PIC12F629T-E/MD PIC12F629T-I/MD PIC12F635-I/MD PIC12F635T-I/MD PIC12F635T-I/MD070 PIC12F635T-I/MD073 PIC12F675-E/MD PIC12F675-I/MD PIC12F675-I/MD176 PIC12F675T-E/MD PIC12F675T-I/MD PIC12F683-E/MD PIC12F683-I/MD PIC12F683T-E/MD PIC12F683T-I/MD PIC12HV609-E/MD PIC12HV609-I/MD PIC12HV609T-I/MD PIC12HV615-E/MD PIC12HV615-I/MD PIC12HV615T-I/MD